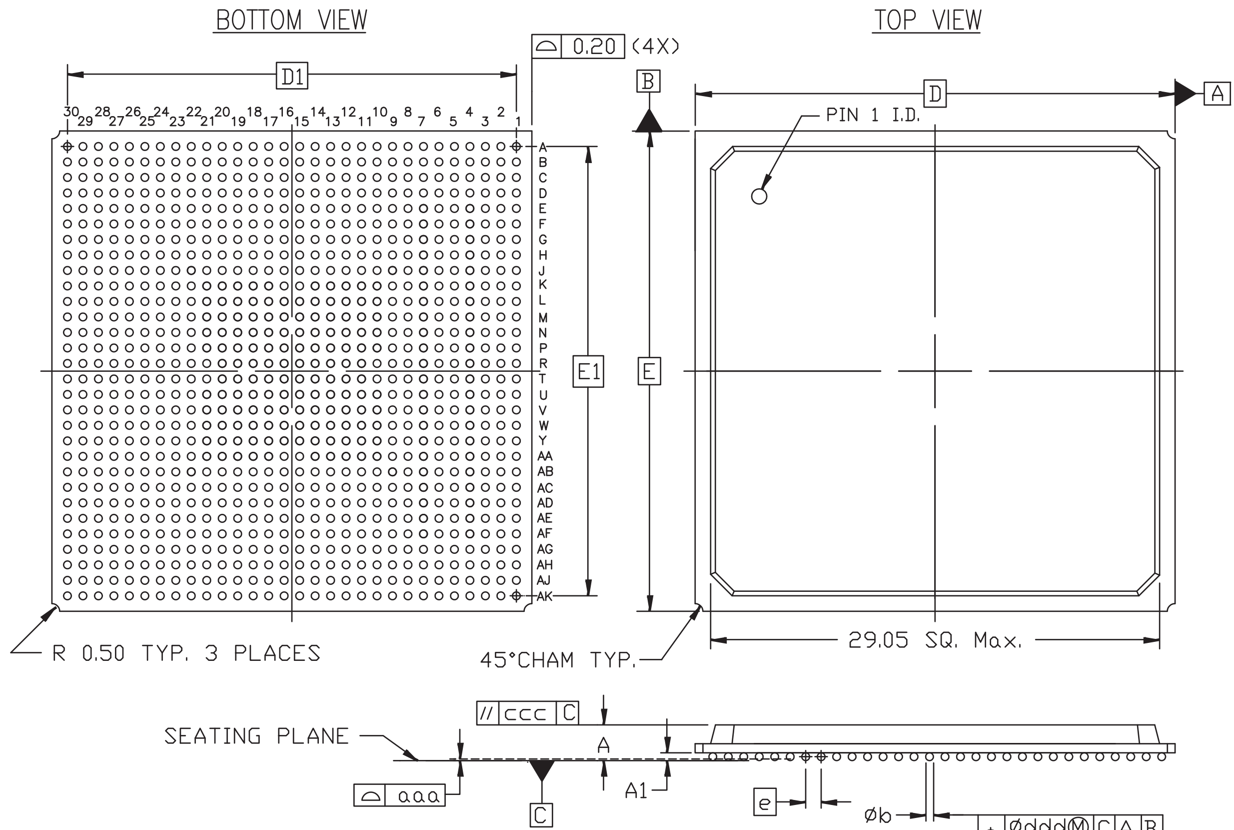
Fine-Pitch BGA (FG900/FGG900) Package



FG900 – 63/37 (Sn/Pb) Solder Balls
FGG900 – Sn/Ag/Cu Solder Balls

SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	~	2.25	2.60
A_1	0.40	0.50	0.60
D/E	31.00 BSC		
D_1/E_1	29.00 REF		
e	1.00 BSC		
Øb	0.50	0.60	0.70
aaa	~	~	0.20
ccc	~	~	0.35
ddd	~	~	0.25
eee	~	~	0.10
M	30		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M–1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS–034–AAN–1

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/12/09	1.3	Removed note 3 regarding component land diameter. This dimension is specified in UG112, Device Package User Guide under Recommended PCB Design Rules.
11/12/09	1.4	Changed symbol ddd value from 0.30 to 0.25 to conform to JEDEC MS-034.

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